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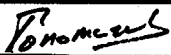
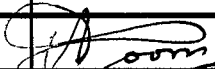
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EXTERNAL VISUAL INSPECTION OF RESISTORS

ESA/SCC Basic Specification No. 2054000



**space components
coordination group**

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		SCCG Chairman	ESA Director General or his Deputy
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DOCUMENTATION CHANGE NOTICE

Rev. Letter	Rev. Date	Reference	CHANGE Item	Approved DCR No.



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**1. SCOPE**

This specification to be read in conjunction with ESA/SCC Basic Specification No. 20500 'External Visual Inspection', contains additional specific requirements for Resistors. They shall apply, where relevant, to each device inspected.

2. GENERAL REQUIREMENTS**2.1 APPLICABILITY**

The following criteria may not be varied or modified after commencing an inspection stage. Any ambiguity or proposed minor deviation shall be referred to the Qualifying Space Agency (QSA) for resolution and approval.

2.2 PROCEDURE

All items shall be examined in such a manner that a minimum of handling and movement of the component is involved.

3. EQUIPMENT REQUIRED**3.1 MAGNIFICATION**

All items shall be examined with a stereoscopic microscope with a minimum magnification of 5 power (5X).

3.2 MOUNTING FIXTURES

Suitable fixtures may be used to assist in the inspection process, provided that they do not themselves cause damage to the device.

4. DETAILED REQUIREMENTS**4.1 REJECT CRITERIA**

A component shall be rejected if it exhibits one or more of the defects listed in any of the following paragraphs of this Section.

Where applicable, drawings are included to provide additional explanatory material, but shall be considered as examples only.

4.2 LEAD CONDITIONS**4.2.1 Non-Insulated Leads**

- (a) Corrosion is evident.
- (b) Plating damage exposing base material beyond 3.0mm from the case.
- (c) Lead diameter is reduced by more than 10% in any part within 20mm of the case.
- (d) Non-conductive material present on the lead, beyond 3.0mm from the case.

4.2.2 Insulated Leads

- (a) Insulation damaged so that metallic conductor is visible.
- (b) Holes or cracks visible in the insulation.

**4.3 LEAD CONFIGURATION**

- (a) Round lead, twisted more than one revolution along the length (Figure I).
- (b) Leads kinked within 20mm of the case (Figure II).
- (c) Eccentricity of lead passing through end of body is greater than 10% of the body diameter:
 $d \geq 0.1 D$ or 0.5mm, whichever is smaller (Figure III).
- (d) Any rigid lead tilted by more than 5° (Figure IV).
- (e) Any lead printed beside 3.0mm of the case (Figure IV).

4.4 CASE OR PACKAGE

- (a) Moulding eccentricity by more than 10% (Figure V).
- (b) Coating or moulding material showing holes or cracks whose depth cannot be determined.
- (c) Coating or moulding material showing holes, cracks or scratches whose surface area exceeds 1% of the total surface area of the moulding or coating material.
- (d) Part of the body or body lead connections are not covered by coating or moulding.
- (e) Coating or moulding chipped and whose chippage area exceeds 5% of the total surface area of the moulding or coating material.
- (f) Any surface contaminated by foreign material.
- (g) Moulding flash or excess of moulding material at the end of the body (Figure VI).

4.5 ADDITIONAL REQUIREMENTS FOR WIREWOUND, CHASSIS-MOUNTED RESISTORS**4.5.1 Housing**

- (a) Contact area between the bottom of the housing and the surface plate is less than 50% (Figure VII).
- (b) Cracks or scratches in plating whose surface area exceeds 5.0mm² (Figure VIII).
- (c) Burrs exceeding 0.5mm (Figure IX).

4.5.2 Ends of the Enclosure (Figure X)

- (a) Caps visible due to a lack of coverage by moulding material.
- (b) Cracks or scratches whose length exceeds one third of the diameter of the enclosure.

4.5.3 Eyelet Terminals (Figure XI)

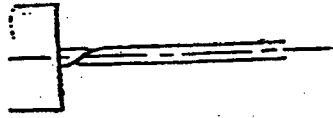
- (a) Hole partially covered by solder.
- (b) Hole eccentricity more than 10%.
- (c) Protuberance exceeding 0.5mm.

4.6 ADDITIONAL REQUIREMENTS FOR VARIABLE RESISTORS

- (a) Head improperly formed or damaged.
- (b) Screw head not fully accessible.
- (c) Screw thread improperly formed or damaged.



FIGURE I - TWISTED LEAD



NOTES

1. See Para. 4.3(a).

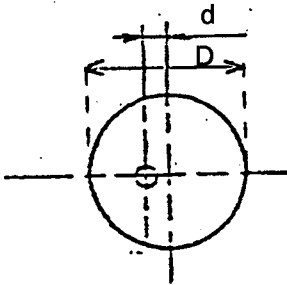
FIGURE II - KINKED LEAD



NOTES

1. See Para. 4.3(b).

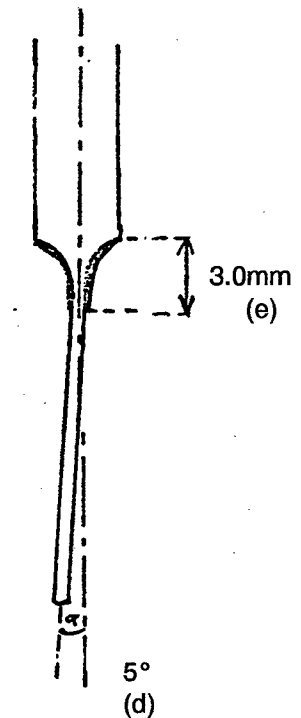
FIGURE III - ECCENTRICITY OF LEAD



NOTES

1. See Para. 4.3(c).

FIGURE IV - TILTED LEAD

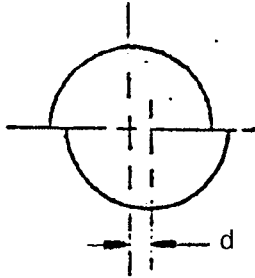


NOTES

1. (d) and (e) relate to Para. 4.3(d) and 4.3.(e) respectively.



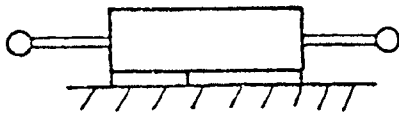
FIGURE V - MOULDING ECCENTRICITY



NOTES

- 1. See Para. 4.4(a).

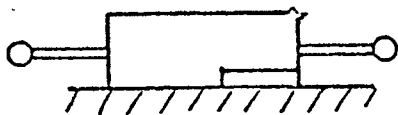
FIGURE VII - CONTACT AREA BETWEEN HOUSING AND PLATE



NOTES

- 1. See Para. 4.5.1(a).

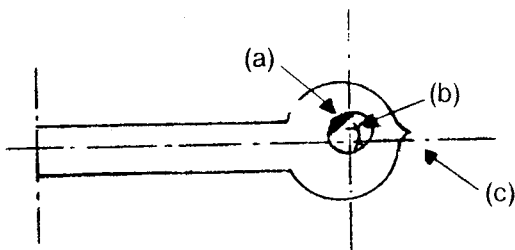
FIGURE IX - BURRS



NOTES

- 1. See Para. 4.5.1(c).

FIGURE XI - EYELET TERMINALS



NOTES

- 1. (a), (b) and (c) relate to Para. 4.5.3(a), (b) and (c) respectively.

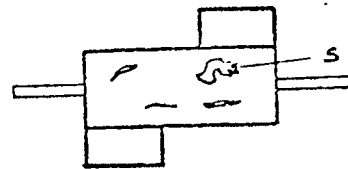
FIGURE VI - MOULDING FLASH



NOTES

- 1. See Para. 4.4(g).

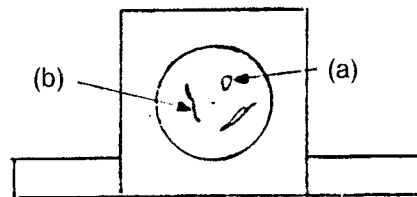
FIGURE VIII - CRACKS AND SCRATCHES IN PLATING



NOTES

- 1. See Para. 4.5.1(b).

FIGURE X - ENDS OF THE ENCLOSURE



NOTES

- 1. See Para. 4.5.2.